

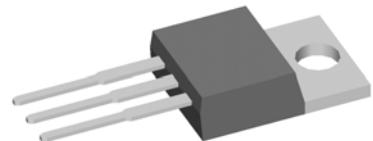
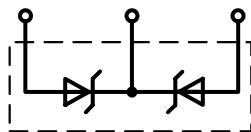
Schottky

High Performance Schottky Diode
Low Loss and Soft Recovery
Common Cathode

V_{RRM} = 60 V
I_{FAV} = 2x 15 A
V_F = 0.69 V

Part number (Marking on product)

DSB 30 C 60PB

**Features / Advantages:**

- Very low V_f
- Extremely low switching losses
- Low I_{rm}-values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

Package:

- TO-220AB
- Industry standard outline
 - Epoxy meets UL 94V-0
 - RoHS compliant

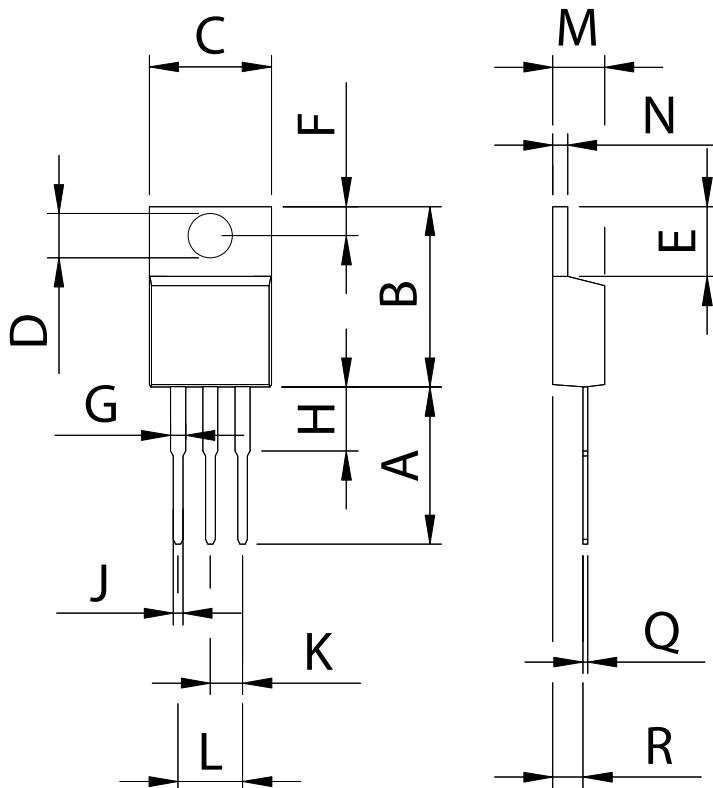
Ratings					
Symbol	Definition	Conditions	min.	typ.	max.
V _{RRM}	max. repetitive reverse voltage	T _{VJ} = 25 °C			60 V
I _R	reverse current	V _R = 60 V T _{VJ} = 25 °C			10 mA
		V _R = 60 V T _{VJ} = 100 °C			30 mA
V _F	forward voltage	I _F =A 15 T _{VJ} = 25 °C			0.78 V
		I _F =A 30			1.21 V
		I _F =A 15 T _{VJ} = 125 °C			0.69 V
		I _F =A 30			0.95 V
I _{FAV}	average forward current	rectangular, d = 0.5 T _C = 125 °C			15 A
V _{F0} r _F	threshold voltage } slope resistance } for power loss calculation only	T _{VJ} = 150 °C			0.45 V
					10.7 mΩ
R _{thJC}	thermal resistance junction to case				1.75 K/W
T _{VJ}	virtual junction temperature		-55		150 °C
P _{tot}	total power dissipation	T _C = 25 °C			70 W
I _{FSM}	max. forward surge current	t _p = 1 0 ms (50 Hz), sine T _{VJ} = 45 °C			150 A
C _J	junction capacitance	V _R = V; f = 1 MHz T _{VJ} = 25 °C			pF
E _{AS}	non-repetitive avalanche energy	I _{AS} =A ; L = 100 µH T _{VJ} = 25 °C			tbd mJ
I _{AR}	repetitive avalanche current	V _A = 1.5·V _R typ.; f = 10 kHz			tbd A

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
I_{RMS}	RMS current	per pin*			35	A
R_{thCH}	thermal resistance case to heatsink			0.50		K/W
M_D	mounting torque		0.4		0.6	Nm
F_c	mounting force with clip		20		60	N
T_{stg}	storage temperature		-55		150	°C
Weight				2		g

* I_{RMS} is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

Outlines TO-220AB



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	12.70	13.97	0.500	0.550
B	14.73	16.00	0.580	0.630
C	9.91	10.66	0.390	0.420
D	3.54	4.08	0.139	0.161
E	5.85	6.85	0.230	0.270
F	2.54	3.18	0.100	0.125
G	1.15	1.65	0.045	0.065
H	2.79	5.84	0.110	0.230
J	0.64	1.01	0.025	0.040
K	2.54	BSC	0.100	BSC
M	4.32	4.82	0.170	0.190
N	1.14	1.39	0.045	0.055
Q	0.35	0.56	0.014	0.022
R	2.29	2.79	0.090	0.110